

Article

Bottom-Up (Cu, Ag, Au)/Al₂O₃/Bi₂Te₃ Assembled Thermoelectric Heterostructures

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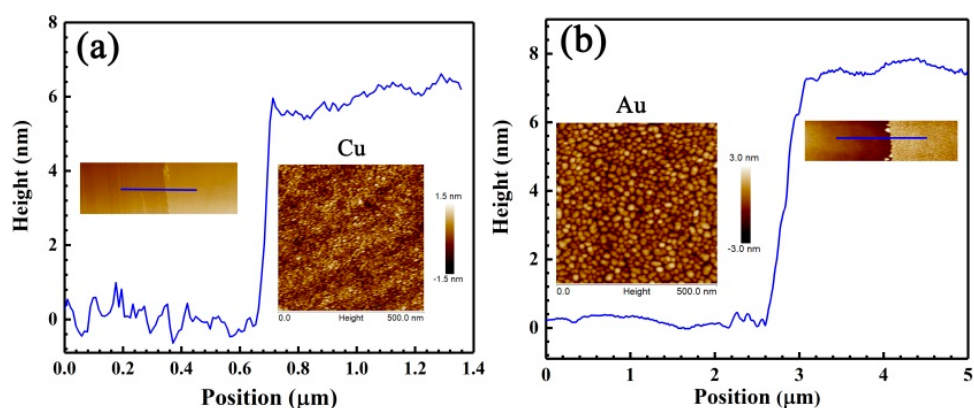


Figure S1 AFM step profiler of (a) Cu and (d) Au.

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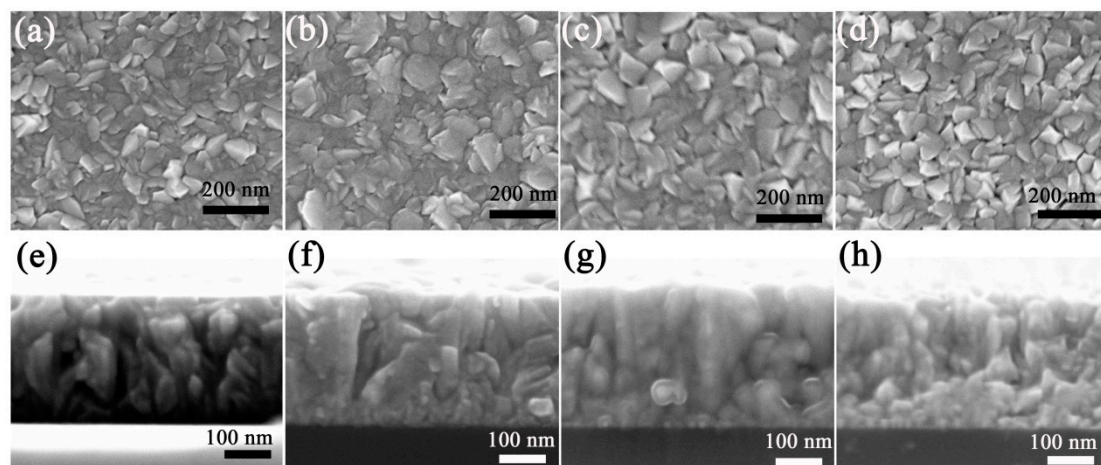


Figure S2 Surface of (a) Bi₂Te₃, (b) Cu/Al₂O₃/Bi₂Te₃, (c) Ag/Al₂O₃/Bi₂Te₃, (d) Au/Al₂O₃/Bi₂Te₃. Cross section of (e) Bi₂Te₃, (f) Cu/Al₂O₃/Bi₂Te₃, (g) Ag/Al₂O₃/Bi₂Te₃, (h) Au/Al₂O₃/Bi₂Te₃.



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